

Title (en)

METHOD AND ARRANGEMENT FOR HEATING A COMPONENT

Title (de)

VERFAHREN UND VORRICHTUNG ZUM HEIZEN VON EINEM BAUTEIL

Title (fr)

PROCEDE ET DISPOSITIF SERVANT A RECHAUFFER UN COMPOSANT

Publication

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Application

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- FI 965301 A 19961231

Abstract (en)

[origin: WO9830075A2] The invention relates to a method and arrangement for heating at least one component (14) of a circuit board comprising one or plural layers (10 and 11). At least one component (14) to be heated is then heated with at least one heat resistor (15) associated with the circuit board.

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H05K 7/20

IPC 8 full level

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